

ABSTRACT

A method and an apparatus for separating elongated semiconductor strips from a wafer of semiconductor material are disclosed. Vacuum is applied to the face of each semiconductor strip forming an edge of the wafer or being adjacent to the edge. The wafer and the source of the vacuum are displaced to separate each elongated semiconductor strip from the wafer. Further, a method and an apparatus for assembling elongated semiconductor strips separated from a wafer of semiconductor material into an array of strips are disclosed. Still further, methods, apparatuses, and systems for assembling an array of elongated semiconductor strips on a substrate are also disclosed.

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